

	Subclass	ISSUE CLASSIFICATION
	Class	

PATENT NUMBER

U.S. UTILITY Patent Application

105	DATE	PATENT DATE
CRANDON	24	11/11/99

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/899627	F	438	687	2000	Quarrell

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TITLE: Solution for chemical mechanical polishing and method of manufacturing copper metal interconnection layer using the same.

PTO-2040
12/99

ISSUE CLASSIFICATION